

## **In the Claims**

### **CLAIMS**

Claim 1 (canceled).

Claim 2 (previously presented): The semiconductor package of claim 7 wherein the dielectric support member is a photomask material.

Claim 3 (previously presented): The semiconductor package of claim 7 wherein the dielectric support member is not a photomask material.

Claim 4 (previously presented): The semiconductor package of claim 7 wherein the one or more circuit traces comprise copper.

Claims 5 and 6 (canceled).

Claim 7 (Currently amended): A semiconductor package, comprising:

an interposer construction comprising a single dielectric support member, a plurality of conductive circuit traces contacting the single dielectric support member, the entire structure of the single dielectric support member is a single layer of dielectric material;

a semiconductor die electrically connected with at least one of the circuit traces;

at least one of the circuit traces being between the semiconductor die and the dielectric support member;

the single dielectric support member having a first surface and an opposing second surface, the plurality of the circuit traces ~~being over~~ comprising an uppermost surface that is coplanar with the first surface, openings extending through the second surface to at least some of the circuit traces, wherein the semiconductor die is spaced from the plurality of the circuit traces by an adhesive structure, and wherein an entirety of the spacing between the uppermost surface of the plurality of the circuit traces and the semiconductor die is completely filled with the adhesive structure;

contact pads within one or more of the openings and in electrical connection with one or more of the circuit traces, the contact pads being entirely contained within the openings wherein an entirety of at least one of the contact pads is elevationally spaced from at least one of the first and the second surfaces of the single dielectric support member; and

solder balls in electrical connection with the contact pads.

Claim 8 (previously presented): The semiconductor package of claim 7 wherein:  
the dielectric support member has a slit extending therethrough; and  
the electrical connection of the semiconductor die to said at least one of the circuit traces includes one or more wire bonds extending from the die, through the slit, and into at least one of the openings.

Claims 9-56 (canceled).

Claim 57 (previously presented): The semiconductor package of claim 7 wherein the entirety of the at least one contact pad is elevationally spaced from the first surface of the dielectric support member.

Claim 58 (previously presented): The semiconductor package of claim 7 wherein the entirety of the at least one contact pad is elevationally spaced from the second surface of the dielectric support member.

Claim 59 (previously presented): The semiconductor package of claim 7 wherein the entirety of the at least one contact pad is elevationally spaced from both of the first and the second surfaces of the dielectric support member.

Claim 60 (Currently amended): The semiconductor package of claim 7 further comprising an wherein the adhesive structure directly ~~contacting~~ contacts the plurality of the circuit traces and directly ~~contacting~~ contacts the semiconductor die, the adhesive structure comprising dielectric material.

Claim 61 (previously presented): The semiconductor package of claim 7 wherein the at least one contact pad comprises at least two conductive layers.

Claim 62 (previously presented): The semiconductor package of claim 7 wherein the interposer construction has a thickness, and wherein the thickness comprises a range from about 15 micrometers to about 150 micrometers.

Claim 63 (previously presented): The semiconductor package of claim 7 wherein the interposer construction has a thickness, and wherein the thickness comprises about 50 micrometers.

Claim 64 (previously presented): The semiconductor package of claim 7 wherein the single dielectric support member comprises at least one of polyimide and liquid polymer crystal.

Claim 65 (Currently amended): The semiconductor package of claim 7 further ~~comprising an~~ wherein the adhesive structure directly ~~contacting~~ contacts the single dielectric support member and directly ~~contacting~~ contacts the semiconductor die, the adhesive structure comprising dielectric material.

Claim 66 (previously presented): The semiconductor package of claim 7 wherein each solder ball is in physical contact with one contact pad.

Claim 67 (previously presented): The semiconductor package of claim 7 wherein a portion of each solder balls rests in one of the openings.

Claim 68 (New): The semiconductor package of claim 7 wherein the adhesive structure directly contacts the plurality of the circuit traces, directly contacts the semiconductor die, and directly contacts the single dielectric support member.